

Amendments to the Claims:

The listing of claims will replace all prior versions, and listings of claims in the application:

Listing of Claims:

Claims 1 – 2 (cancelled)

Claim 3. (withdrawn) A tube electroforming method comprising the steps of: forming an electrodeposit material or a surrounding material by electroforming around a thin wire material made of stainless steel including a conductive layer which is a different metal layer from the electrodeposit material or the surrounding material disposed on an outer surface of the thin wire material; and removing the thin wire material so as to maintain the conductive layer on an inner surface of the electrodeposit material or the surrounding material,

wherein the conductive layer is formed by electrolytic plating and has a higher electrical conductivity than that of the electrodeposit material or the surrounding material, and

the thin wire material is removed by pulling the material from one end or both ends.

Claim 4. (cancelled)

Claim 5. (withdrawn) The tube electroforming method according to claim 3,

wherein a deformation amount of a lateral distortion at a time when the thin wire material is pulled and extended outwards is 5% or more of the sectional area.

Claims 6 – 7 (cancelled)

Claim 8. (withdrawn) The tube electroforming method according to claim 3,

wherein the thin wire material is used in which at least two conductive layers constituted of different materials are formed on an outer surface of the material, the electrodeposit material or the surrounding material is brought into close contact with the outer conductive layer of the thin wire material, and the thin wire material is removed so that the inner conductive layer remains on an inner surface of the tube by electroforming.

Claim 9. (withdrawn) The tube electroforming method according to claim 3,

wherein an inner shape of a hollow portion formed by removing the thin wire material from the electrodeposit material or the surrounding material has a circular sectional shape or a polygonal sectional shape.

Claims 10 – 35 (cancelled)

Claim 36. (currently amended) A tube produced by electroforming through forming an electrodeposit material or a surrounding material by electroforming around a thin wire material including a conductive layer which is a different metal layer from the electrodeposit material or the surrounding material disposed on an outer surface of the thin wire material, pulling the thin wire material from one end or both ends to deform the thin wire material so that a sectional area thereof is reduced, forming a clearance between the thin wire material and the conductive layer to extract the thin wire material, and removing the thin wire material so as to maintain the conductive layer on an inner surface of the electrodeposit material or the surrounding material,

wherein the tube has a hollow portion with a fine diameter for a contact probe to inspect an electric conduction in a semiconductor manufacturing technology,

the conductive layer is a plated layer formed by electrolytic plating and has a higher electrical conductivity than that of the electrodeposit material or the surrounding material, and

the a-hollow portion is formed by removing the thin wire material from the electrodeposit material or the surrounding material, a thickness of the electrodeposit material or the surrounding material is 5 μm or more and 50 μm or less, when an inner shape of the hollow portion has a circular sectional shape.

Claim 37. (previously presented) The tube according to claim 36, having an inner diameter of the hollow portion is 10 μm or more and 85 μm or less.

Claim 38. (currently amended) A tube produced by electroforming through forming an electrodeposit material or a surrounding material by electroforming around a thin wire material including a conductive layer which is a different metal layer from the electrodeposit material or the surrounding material disposed on an outer surface of the thin wire material, pulling the thin wire material from one end or both ends to deform the thin wire material so that a sectional area thereof is reduced, forming a clearance between the thin wire material and the conductive layer to extract the thin wire material, and removing the thin wire material so as to remain the conductive layer on an inner surface of the electrodeposit material or the surrounding material,

wherein the tube has a hollow portion with a fine diameter for a contact probe to inspect an electric conduction in a semiconductor manufacturing technology.

the conductive layer is a plated layer formed by electrolytic plating and has a higher electrical conductivity than that of the electrodeposit material or the surrounding material, and

the a-hollow portion is formed by removing the thin wire material from the electrodeposit material or the surrounding material, a thickness of the electrodeposit material or the surrounding material is 5 μm or more and 50 μm or less, when an inner shape of the hollow portion has a polygonal sectional shape.

Claim 39. (previously presented) The tube according to claim 38, having a diameter of an inscribed circle of the hollow portion is 10 μm or more and 85 μm or less, when the inner shape of the hollow portion has a polygonal sectional shape.